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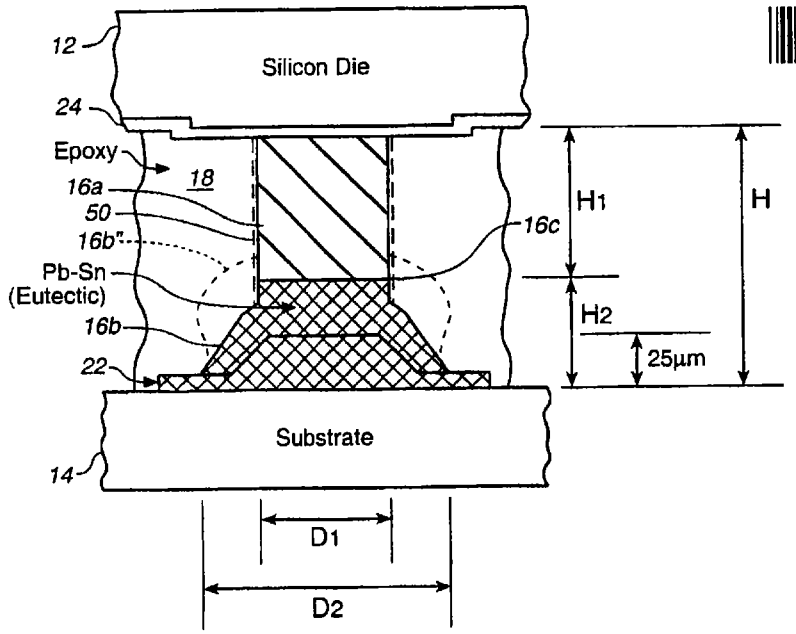
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(54) Title: IMPROVED PILLAR CONNECTIONS FOR SEMICONDUCTOR CHIPS AND METHOD OF MANUFACTURE



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(57) Abstract: A flip chip interconnect system comprises an elongated pillar comprising two elongated portions, a first portion including solder with or without lead and a second portion including copper or gold or other material having higher reflow temperature than the first portion. The second portion is to be connected to the semiconductor chip and has a length preferably of more than 55 microns to reduce the effect of α particles from the solder from affecting electronic devices on the chip. The total length of the pillar is preferably in the range of 80 to 120 microns.

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